



Ultra High Performance BGA Cooling Solutions w/ maxiGRIP™ Attachment

ATS PART # ATS-50450B-C2-R0

Features & Benefits

- » maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- » maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB
- » Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock and Unpackaged Drop Testing standards
- » Comes preassembled with high performance thermal interface material
- » Designed for standard height components from 3 to 4.5mm



*Image above is for illustration purposes only.

Thermal Performance

| AIR VELOCITY | | THERMAL RESISTANCE | |
|--------------|-----|----------------------|--------------------|
| FT/MIN | M/S | °C/W (UNDUCTED FLOW) | °C/W (DUCTED FLOW) |
| 200 | 1.0 | 4 | 2.6 |
| 300 | 1.5 | 2.9 | |
| 400 | 2.0 | 2.4 | |
| 500 | 2.5 | 2.1 | |
| 600 | 3.0 | 1.9 | |
| 700 | 3.5 | 1.8 | |
| 800 | 4.0 | 1.6 | |

Product Details

| DIMENSION A | DIMENSION B | DIMENSION C | DIMENSION D | INTERFACE MATERIAL | FINISH |
|-------------|-------------|-------------|-------------|--------------------|---------------|
| 45 mm | 45 mm | 7.5 mm | 61.5 mm | SAINT-GOBAIN C675 | BLUE-ANODIZED |

NOTES:

- 1) Dimension C = heat sink height from bottom of the base to the top of the fin field.
- 2) Thermal performance data are provided for reference only. Actual performance may vary by application.
- 3) ATS reserves the right to update or change its products without notice to improve the design or performance.
- 4) Optional maxiGRIP™ Installation/Removal Tool Set P/N: MGT450
- 5) Contact ATS to learn about custom options available.



ATS ADVANCED THERMAL SOLUTIONS, INC.
Innovations in Thermal Management®

For more information, to find a distributor or to place an order, visit www.qats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).